Zytel® HTNFR52G45NHF BK337 (PRELIMINARY)

HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTNFR52G45NHF BK337 is a 45% Glass Reinforced, Flame Retardant, High Performance Polyamide with improved flow. It is also a PPA resin and it uses a non-halogenated flame retardant.

Product information

Resin Identification	PA6T/66-GF45FR(40)	ISO 1043
Part Marking Code	>PA6T/66-GF45FR(40)<	ISO 11469
Part Marking Code	>PPA-GF45FR<	SAE J1344
ISO designation	ISO 16396-PA6T/66,GF45 FR(40),M1CF1G,S10-160	

Rheological properties

	dry/cond.		
Moulding shrinkage, parallel	0.2/-	%	ISO 294-4, 2577
Moulding shrinkage, normal	0.6/-	%	ISO 294-4, 2577

Typical mechanical properties

	dry/cond.		
Tensile Modulus	15700/-	MPa	ISO 527-1/-2
Stress at break	174/-	MPa	ISO 527-1/-2
Strain at break	1.8/-	%	ISO 527-1/-2
Flexural Modulus	15600/-	MPa	ISO 178
Flexural Strength	255/-	MPa	ISO 178
Charpy impact strength, 23°C	47/-	kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C	45/-	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	8/-	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C	8/-	kJ/m²	ISO 179/1eA
Poisson's ratio	0.33/-	-	

Thermal properties

	dry/cond.		
Melting temperature, first heat	310/*	°C	ISO 11357-1/-3
Temp. of deflection under load, 1.8 MPa	283/*	°C	ISO 75-1/-2
CLTE, Parallel, -40-23°C	15/*	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, parallel	17/*	E-6/K	ISO 11359-1/-2
CLTE, Parallel, 55-160°C	15/*	E-6/K	ISO 11359-1/-2
CLTE, Normal, -40-23°C	50/*	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, normal	55/*	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, Normal, 55-160°C	95/*	E-6/K	ISO 11359-1/-2
RTI, electrical, 0.4mm	140	°C	UL 746B
RTI, electrical, 0.75mm	140	°C	UL 746B
RTI, electrical, 1.5mm	140	°C	UL 746B
RTI, electrical, 3mm	140	°C	UL 746B
RTI, strength, 0.75mm	125	°C	UL 746B
RTI, strength, 1.5mm	125/*	°C	UL 746B
RTI, strength, 3mm	130	°C	UL 746B

Zytel® HTNFR52G45NHF BK337 (PRELIMINARY)

HIGH PERFORMANCE POLYAMIDE RESIN

Flammability

	dry/cond.		
Burning Behav. at thickness h	V-0/*	class	IEC 60695-11-10
Thickness tested	0.4/*	mm	IEC 60695-11-10
UL recognition	yes/*	-	UL 94

Electrical properties

	dry/cond.		
Volume resistivity	>1E13/-	Ohm.m	IEC 62631-3-1

Other properties

	dry/cond.		
Density	1610/-	kg/m³	ISO 1183

Injection

Drying Recommended	yes	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	6 - 8	h
Processing Moisture Content	≤0.1	%
Min. melt temperature	320	°C
Max. melt temperature	325	°C
Min. mould temperature	90	°C
Max. mould temperature	130	°C

Characteristics

Additives	Flame retardant, Non-halogenated/Red phosphorous free flame retardant

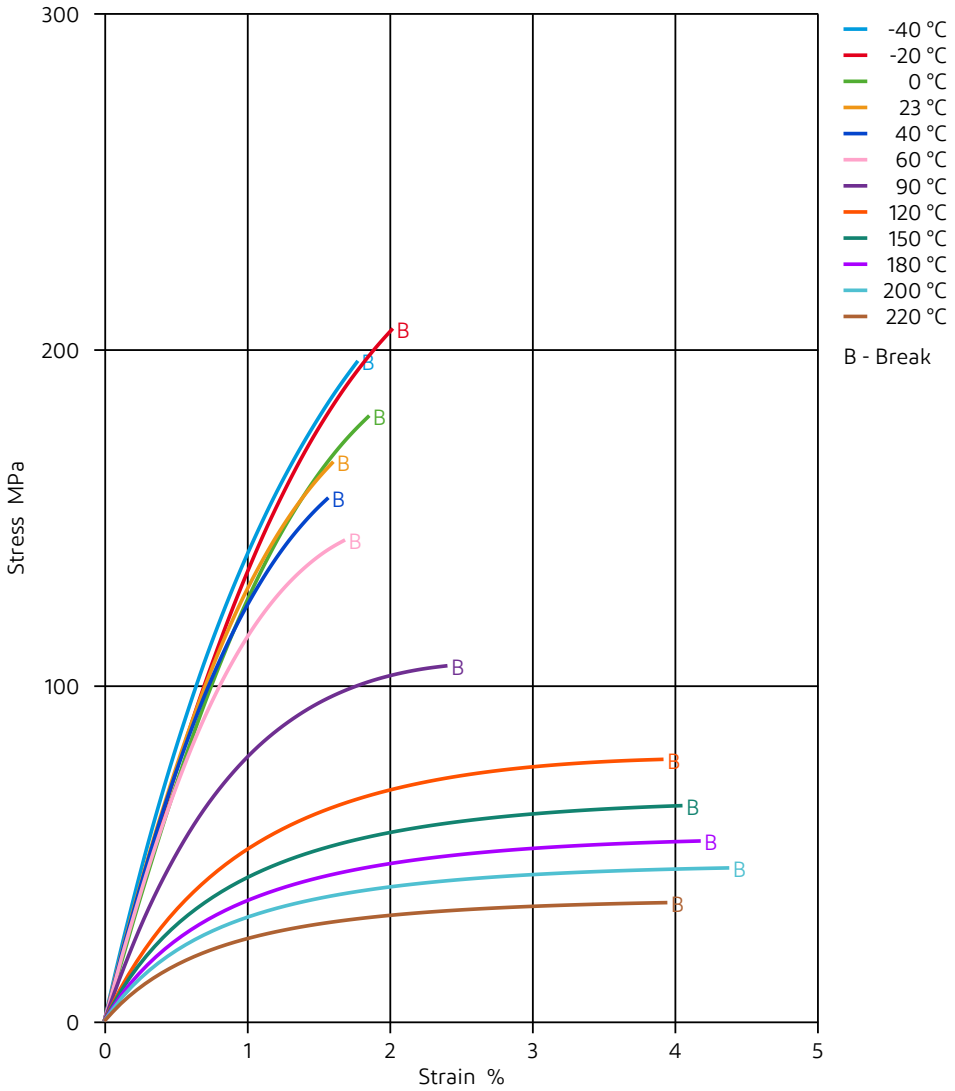
Additional Information

Injection molding	For molding machine components, use corrosion resistant and wear resistant steel. For details please contact your DuPont representative. Limit the residence time of the resin in the machine. Use proper protective equipment and adequate ventilation.

Zytel® HTNFR52G45NHF BK337 (PRELIMINARY)

HIGH PERFORMANCE POLYAMIDE RESIN

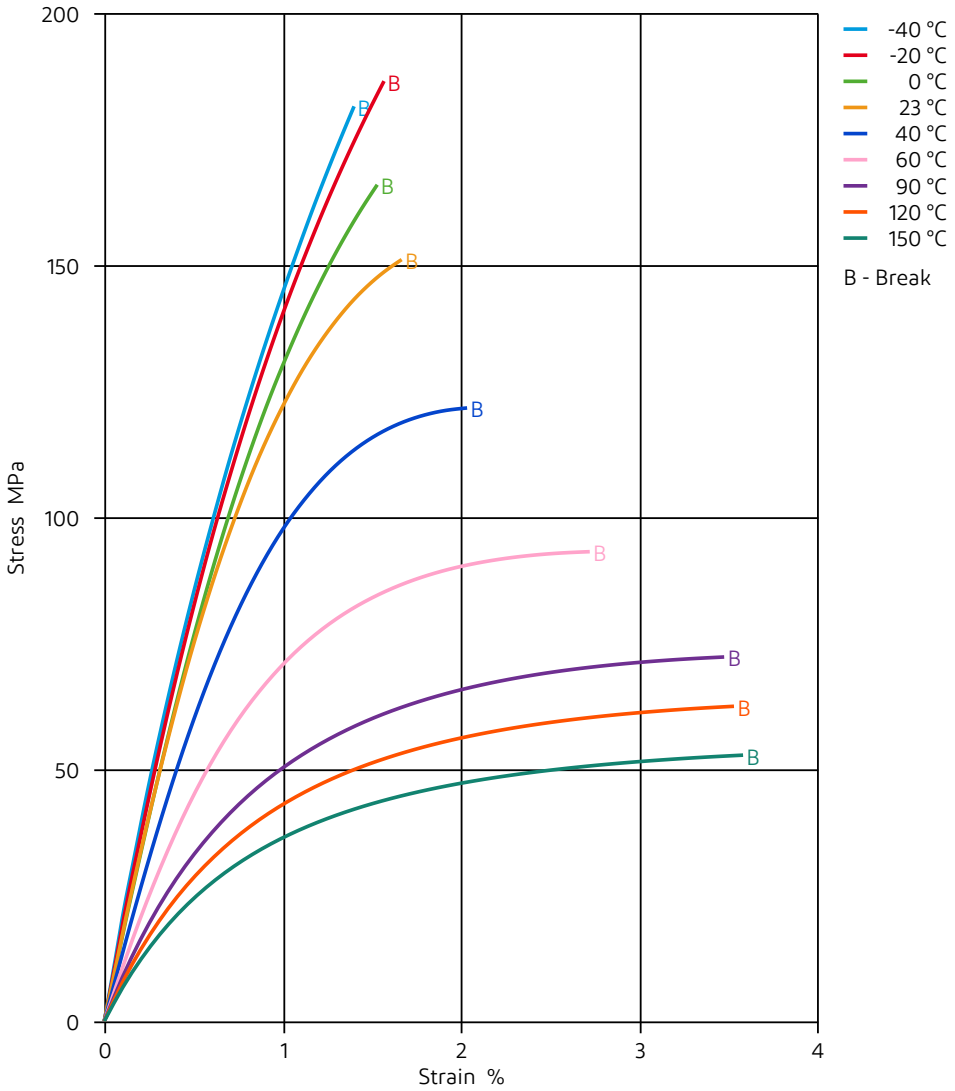
Stress-strain (dry)



Zytel® HTNFR52G45NHF BK337 (PRELIMINARY)

HIGH PERFORMANCE POLYAMIDE RESIN

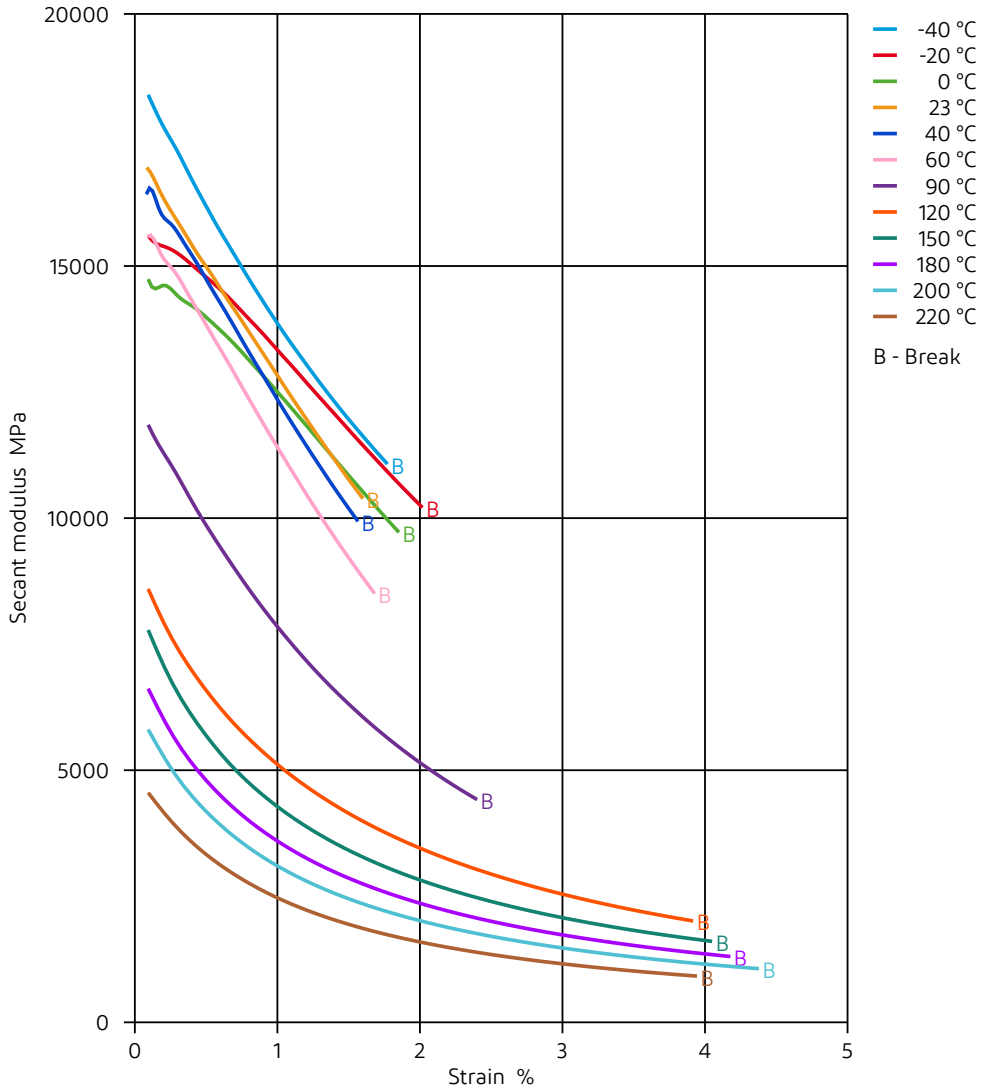
Stress-strain (cond.)



Zytel® HTNFR52G45NHF BK337 (PRELIMINARY)

HIGH PERFORMANCE POLYAMIDE RESIN

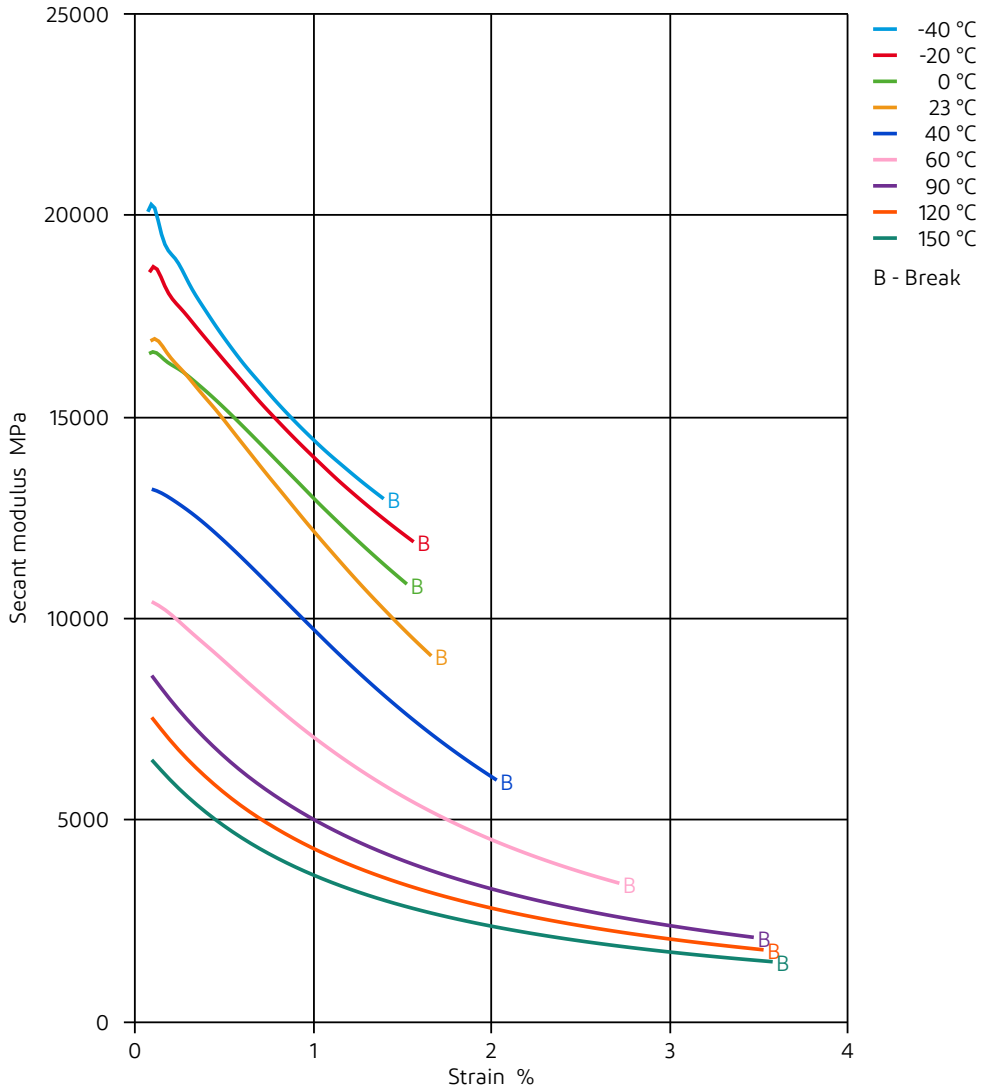
Secant modulus-strain (dry)



Zytel® HTNFR52G45NHF BK337 (PRELIMINARY)

HIGH PERFORMANCE POLYAMIDE RESIN

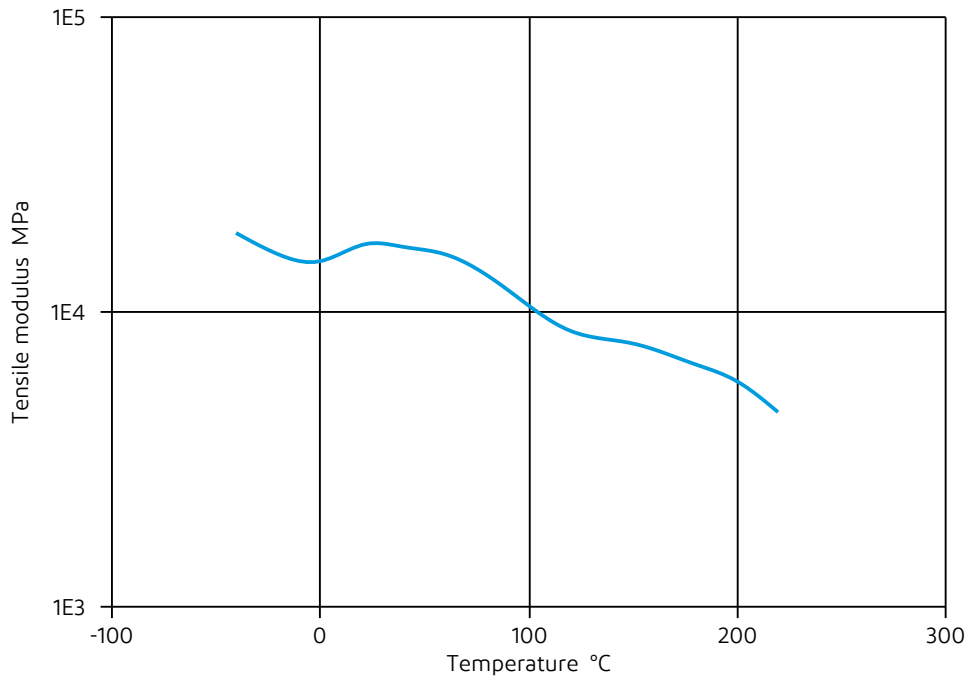
Secant modulus-strain (cond.)



Zytel® HTNFR52G45NHF BK337 (PRELIMINARY)

HIGH PERFORMANCE POLYAMIDE RESIN

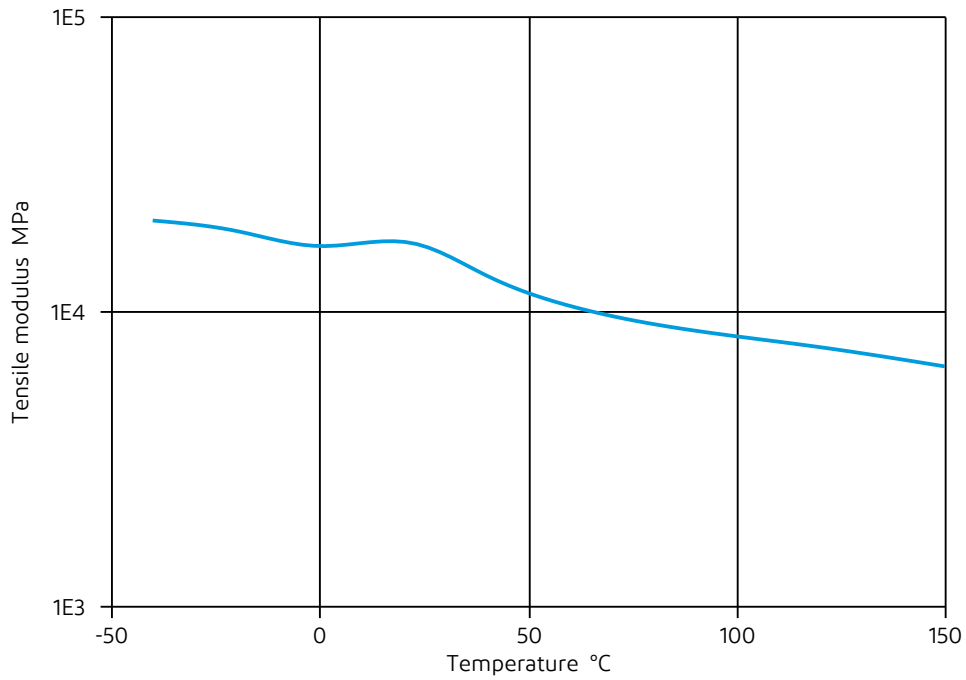
Tensile modulus-temperature (dry)



Zytel® HTNFR52G45NHF BK337 (PRELIMINARY)

HIGH PERFORMANCE POLYAMIDE RESIN

Tensile modulus-temperature (cond.)



dupont.com